

Abstract

Apparatus for mounting a transducer in a wire bonder

Disclosed is an apparatus for mounting a transducer to a bond head of a wire bonder. In particular, the bond head of the wire bonder is operative to mechanically drive the transducer when forming electrical interconnections between separate locations within a semiconductor package. Specifically, the apparatus comprises: i) a flexural structure having a connector for connecting to the transducer, the flexural structure being configured to bend; and ii) at least one actuator attached to the flexural structure, the at least one actuator being operative to bend the flexural structure to thereby cause a displacement of the transducer connected thereto via the connector.

[FIG. 1]